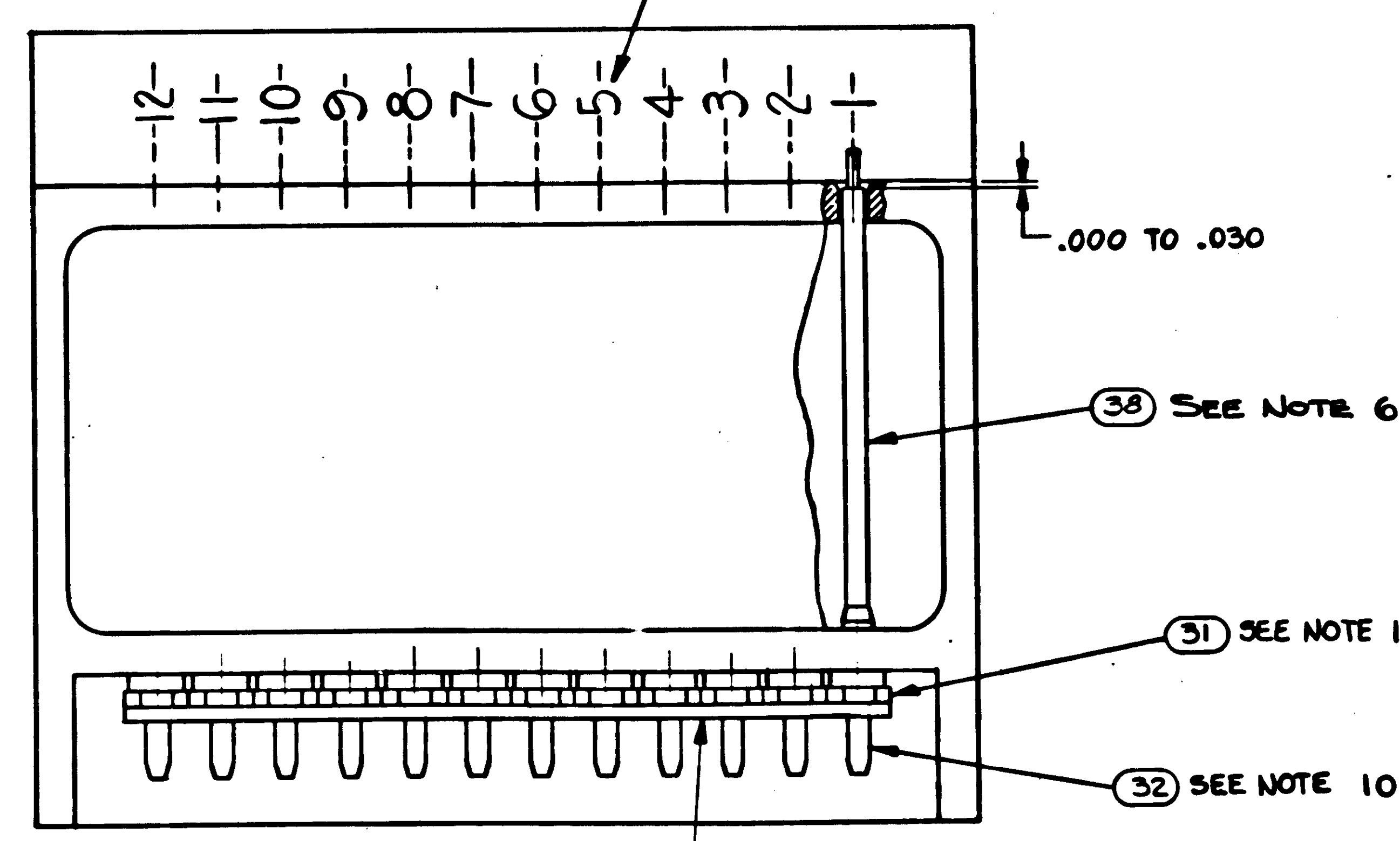


- INTERPRET DRAWING IN ACCORDANCE WITH STANDARDS PRESCRIBED BY MIL-D-70327.
- UNLESS OTHERWISE SPECIFIED: WIRING SHALL MEET THE REQUIREMENTS OF ND 1002069.
- ENCAPSULATE MODULE PER ND1002002 (BLACK POLYURETHANE FOAM) UNLESS OTHERWISE SPECIFIED PERIPHERAL ENCAPSULANT DIMENSIONS MAY EXCEED THE NOMINAL HEATSINK WIDTH AND LENGTH DIMENSIONS BY A MAXIMUM OF .005. WHEN THE HEATSINK OUTLINE EXCEEDS THE ENCAPSULANT OUTLINE, THE MAXIMUM DIMENSION BETWEEN ANY HEATSINK SURFACE AND ITS RESPECTIVE ENCAPSULANT SURFACE SHALL NOT EXCEED .015. REMOVE ALL FLASHING
- MARK PIN NUMBERS  $\frac{100}{660}$  HIGH (WHITE) AND ALL OTHER CHARACTERS  $\frac{140}{100}$  HIGH (WHITE) PER ND 1002019 AND SERIALIZE PER ND 1002023. CENTRALIZE AS SHOWN.
- AREA TO BE FREE OF ENCAPSULATING COMPOUND
- USE AS REQUIRED
- ON ITEMS (2), (3) AND (4):
  - "K" INDICATES CATHODE SIDE OF DIODE
  - FT ( ) INDICATES FEED THRU
  - "C" INDICATES COLLECTOR LEAD OF TRANSISTOR
  - B = BASE
  - E = EMITTER
  - C = COLLECTOR
  - D = BASE
  - E = EMITTER
- WHITE DOT AND CLEAR WIRING INDICATES LOWER LEVEL WIRING. BLACK DOT AND CROSS-HATCHED WIRING INDICATES UPPER LEVEL WIRING.
- TYPICAL SLEEVING FOR CR1 THRU CR4, R1 THRU R8, R14, R16 AND R18
- MUST MEET REQUIREMENTS OF ND1002136
- TORQUE TO 4  $\pm$  1 IN-LB FOR ASSY OF ITEM 10
- ALL CONNECTIONS TO BE MADE BY WELDING PER ND1002005
- ~~BOND ITEM (40) TO ITEM (31) PER ND1002297.~~
- COMPONENTS TO BE CEMENTED IN PLACE PER ND 1002009 METHOD J AND CENTRALIZED
- USE MIL-1-631 TYPE F, FORM U, GRADE C, CLASS I, CATAGORY I, ONE PLACE ONLY. BOND IN PLACE PER ND1002004, TYPE I
- PROCURE PER PS 1007041
- FILL PER ND 1002117
- ~~BOND A .25 MIN. WIDE PERIMETER OF THE TOP AND BOTTOM INSULATORS TO THE HEATSINK AND COAT A .25 MIN. WIDE PERIMETER ON THE OUTSIDE SURFACE OF THE INSULATORS PER ND 1002187 TYPE F.~~

19. CLEAN MODULE WHERE POSSIBLE PRIOR TO BONDING OF WAFER BOARDS AND APPLICATION OF COATING MATERIAL BY DEGREASING WITH FREON AND ISO-PROPYL ALCOHOL. ADHESIVE AND COATING MATERIAL PER ND 1002187 TYPE II. APPLY MATERIAL AND COATING AS INDICATED IN TABLE I.
20. EXCEPT FOR MODULE MOUNTING SURFACE. PAINT ALL SURFACES PER ND 1002279, USING 1010992 PRIMER AND 1008809-4 PAINT. CONNECTOR PIN BLADES AND INSULATORS TO BE FREE OF PAINT.
21. CLEAN MODULE WHERE POSSIBLE BY DEGREASING WITH FREON & ISO-PROPYL ALCOHOL PRIOR TO ENCAPSULATION.



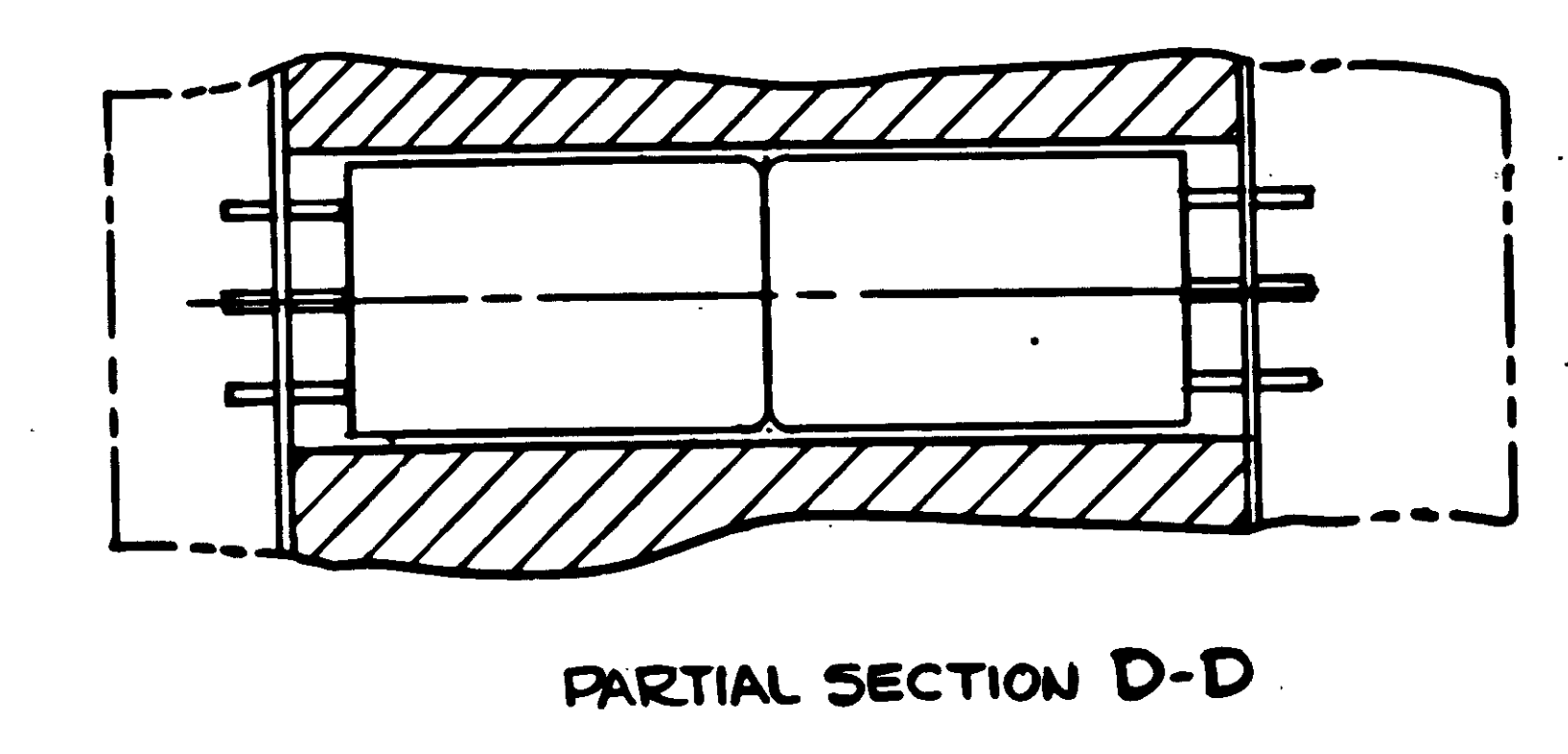
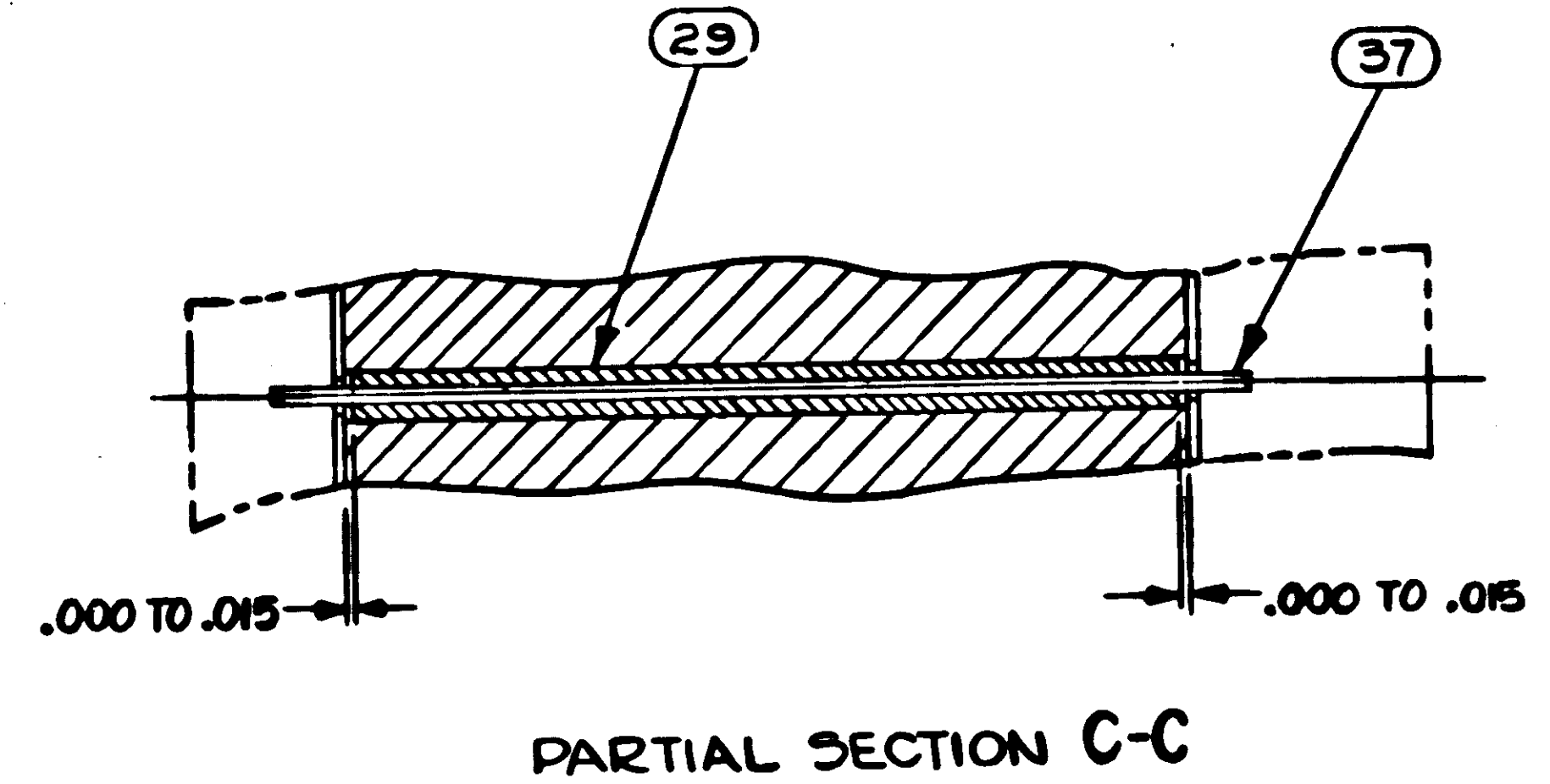
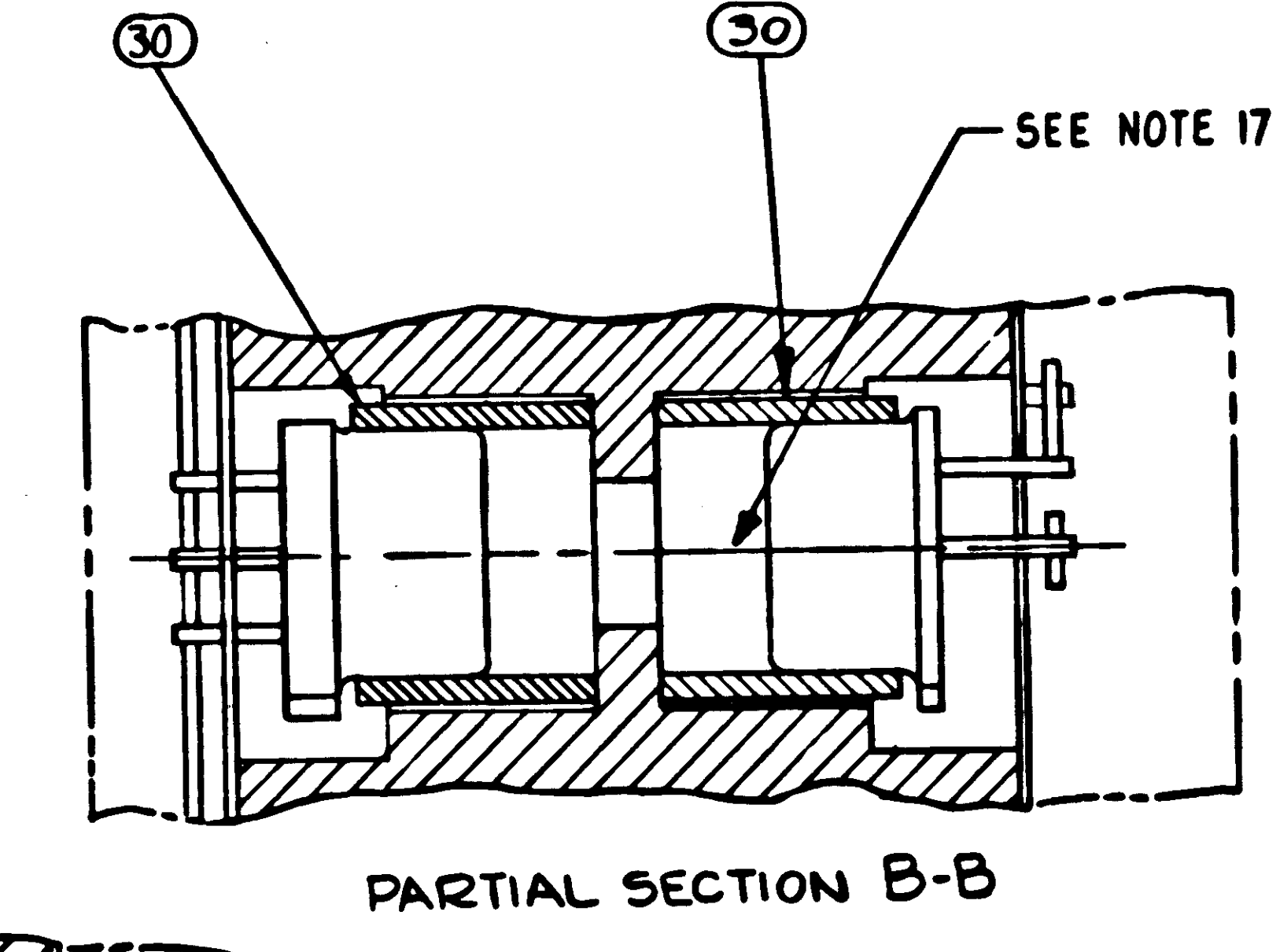
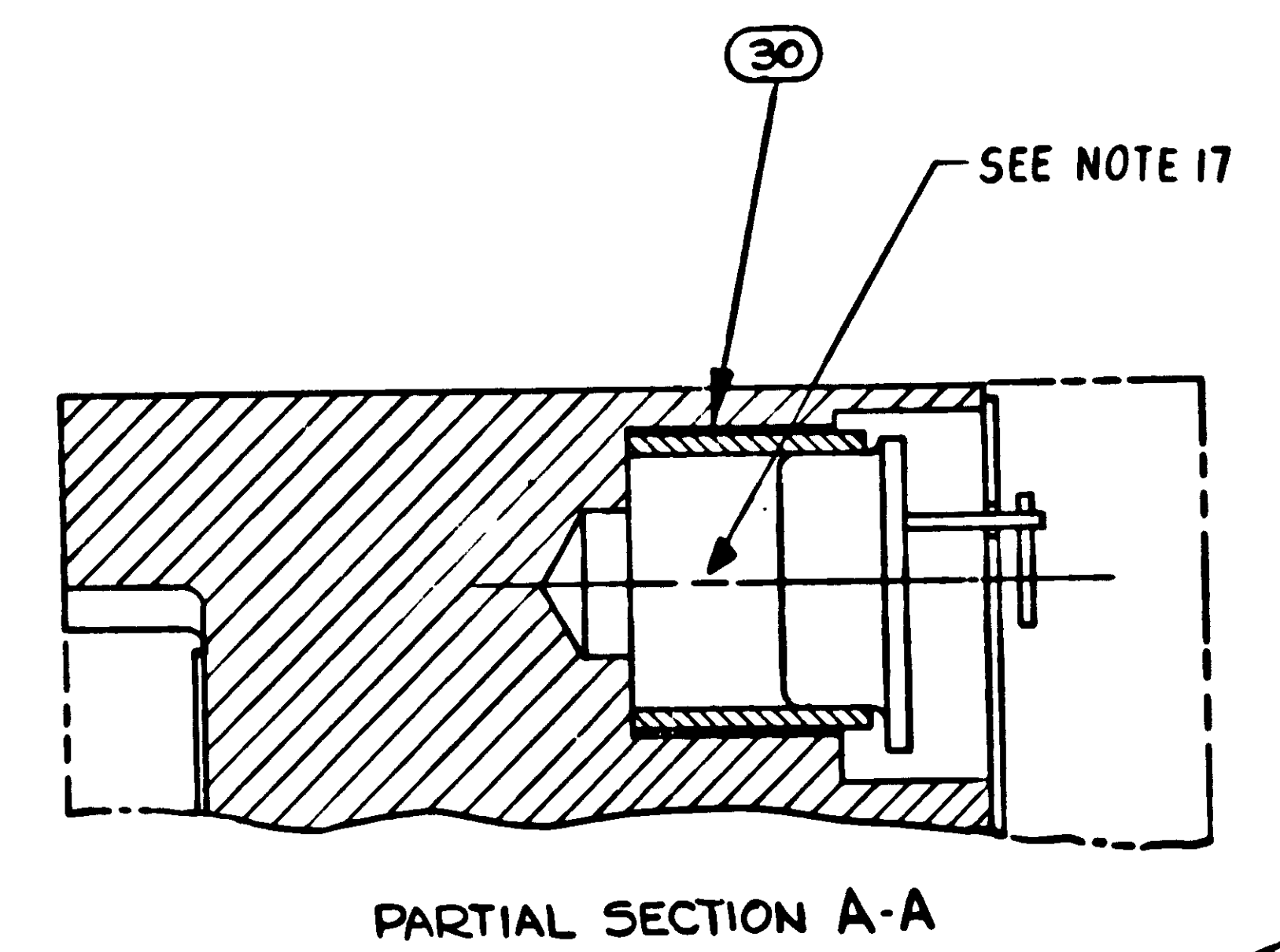
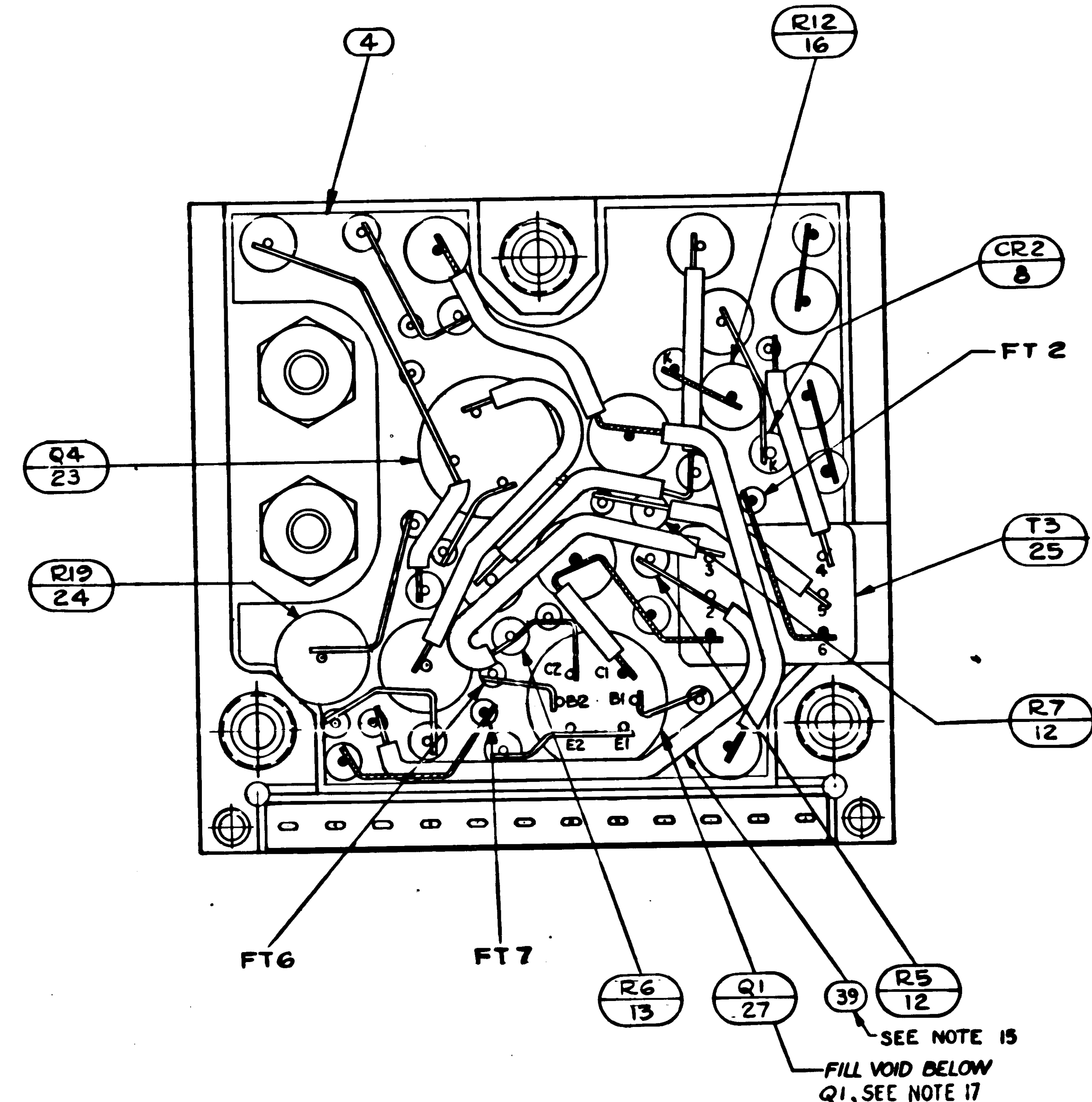
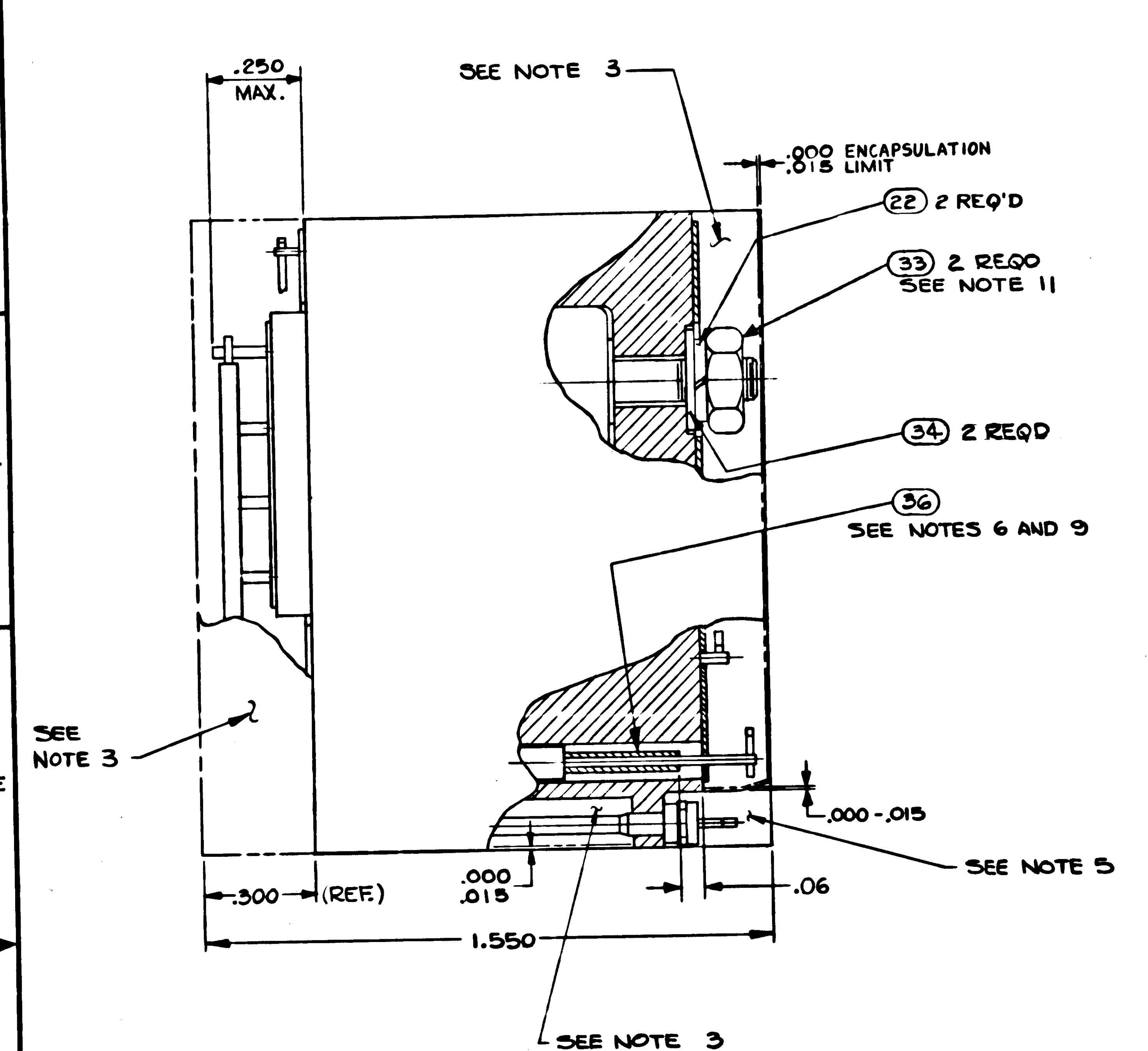
REVISIONS					
REV	ZONE	DESCRIPTION	DATE	APP'D	BY
A		REVISED PER TDRR 17581	2/25/65		
B		REVISED PER TDRR 19403	2/25/65		
C		REVISED PER TDRR 19429	3/2/65		
D		REVISED PER TDRR 19507	3/2/65		
E		REVISED PER TDRR 20143	2/25/65		
F		REVISED PER TDRR 22949	2/25/65		

CONFIGURATION	BOND BETWEEN WAFER AND HEATSINK	TOPOF WAFER	HEATSINK-FOAM/CONTACT SURFACE ADJACENT TO HEATSINK EXTER SURFACE
WAFER & FLAT HEATSINK	100% OF AREA 18 FROM EXTERNAL HEATSINK SURFACE 80% OF AREA 28 FROM EXTERNAL HEATSINK SURFACE	100% OF AREA 25 FROM EXTERNAL WAFER SURFACE	N/A
WAFER AND ADJACENT VERTICAL HEATSINK SURFACE	CORNER FILLET AND VERTICAL SURFACE TO WITHIN .03 $\pm$ .03 OF EXTERNAL SURFACE	100% OF AREA 25 FROM INTERNAL WAFER SURFACE	N/A
HEATSINK FOAM CONTACT SURFACE/PERIMETER	N/A	N/A	.25 MIN WIDTH OR TOTAL AVAILABLE ON 80% OF PERIMETER 10 WITHIN .03 $\pm$ .03 OF EXTERNAL SURFACE

QTY	REF	DESCRIPTION	UNIT
1	40	1008540-12	GASKET, CONNECTOR MINATURE
1	39	MIL-1-631	INSULATION, SLEEVING 22 GA
1	38	1006776-20	INSULATION SLEEVING
1	37	1006757-8	WIRE, ELEC.
1	36	1006776-21	INSULATION SLEEVING
1	35	1006757-7	WIRE, ELEC.
2	34	1008070-5	WASHER, FLAT
2	33	MS20341-4A	NUT, HEX
12	32	1006782-5	CONTACT, WRAPOST MALE MINIA
12	31	1006775	INSULATOR, WRAPOST MALE MINIA
3	30	1008025-2	INSULATOR, BUSHING
29	29	1006776-22	INSULATION SLEEVING
2	28	1010270	TRANSISTOR
1	27	1010252-1	TRANSISTOR
1	26	1010326	TRANSFORMER
2	25	1010329-1	TRANSFORMER
2	24	1010278-7	RESISTOR, FIXED
1	23	1010345-1	TRANSISTOR
2	22	MS35338-78	WASHER, LOCK
1	21	1010364-543	RESISTOR, FIXED
1	20	1006750-56	RESISTOR
1	19	1010364-765	RESISTOR, FIXED
1	18	1010369-105	RESISTOR, FIXED
1	17	1010364-579	RESISTOR, FIXED
4	16	1010364-445	RESISTOR, FIXED
1	15	1006750-45	RESISTOR
1	14	1006750-48	RESISTOR
2	13	1010369-97	RESISTOR, FIXED
4	12	1006750-73	RESISTOR
1	11	1006750-80	RESISTOR
1	10	1010353-1	RELAY, ELECTROMAGNETIC
1	9	1010372-22	DIODE, SEMICONDUCTOR DEVICE
4	8	1010392-1	DIODE, SEMICONDUCTOR DEVICE
1	7	1010279-232	CAPACITOR, FIXED
1	6	1010279-228	CAPACITOR, FIXED
1	5	1010264-15	CAPACITOR, FIXED
1	4	1015692	INSULATOR
1	3	1015690	INSULATOR
1	2	1015691	INSULATOR
1	1	1015689	HEATSINK

1007541	USED ON	APPLICABLE DASH NO.	80230 E	1007541
THE ASSEMBLY PART NUMBER IS THE DRAWING NUMBER AND THE DASH NUMBER THAT APPLIES			SCALE 2:1	SHEET 1 OF 2

REVISIONS					
SYMBOL	DESCRIPTION	CHG NO.	DATE	APPD.	
Δ	REVISED PER TDRR 17331		12 JUN 65	CM	
B	REVISED PER TDRR 19403		12 JUN 65		
C	REVISED PER TDRR 19429		3 JUL 65		
D	REVISION STATUS CHG PER DOC 152		17 JUL 65		
E	REVISION STATUS CHANGE		17 JUL 65		
F	REVISED PER TDRR 22349		17 JUL 65		



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES OR FRACTIONS DECIMALS ANGLES	INSTRUMENTATION LAB Houston, Texas	MANAGED SPACECRAFT CENTER HOUSTON TEXAS
DO NOT SCALE THIS DRAWING	DESIGN: <i>Chapel</i> CHECKED: <i>W. J. ...</i> APPROVAL: <i>...</i>	GIMBAL COURSE ALIGN AMPLIFIER MODULE ASSY
MATERIAL:	NASA APPROVAL: <i>...</i> MIT APPROVAL: <i>...</i>	CODE IDENT NO. 80230 SCALE 5:1
CONTRACT NAS 9-497		1007541 SHEET 2 OF 2

B1007541E